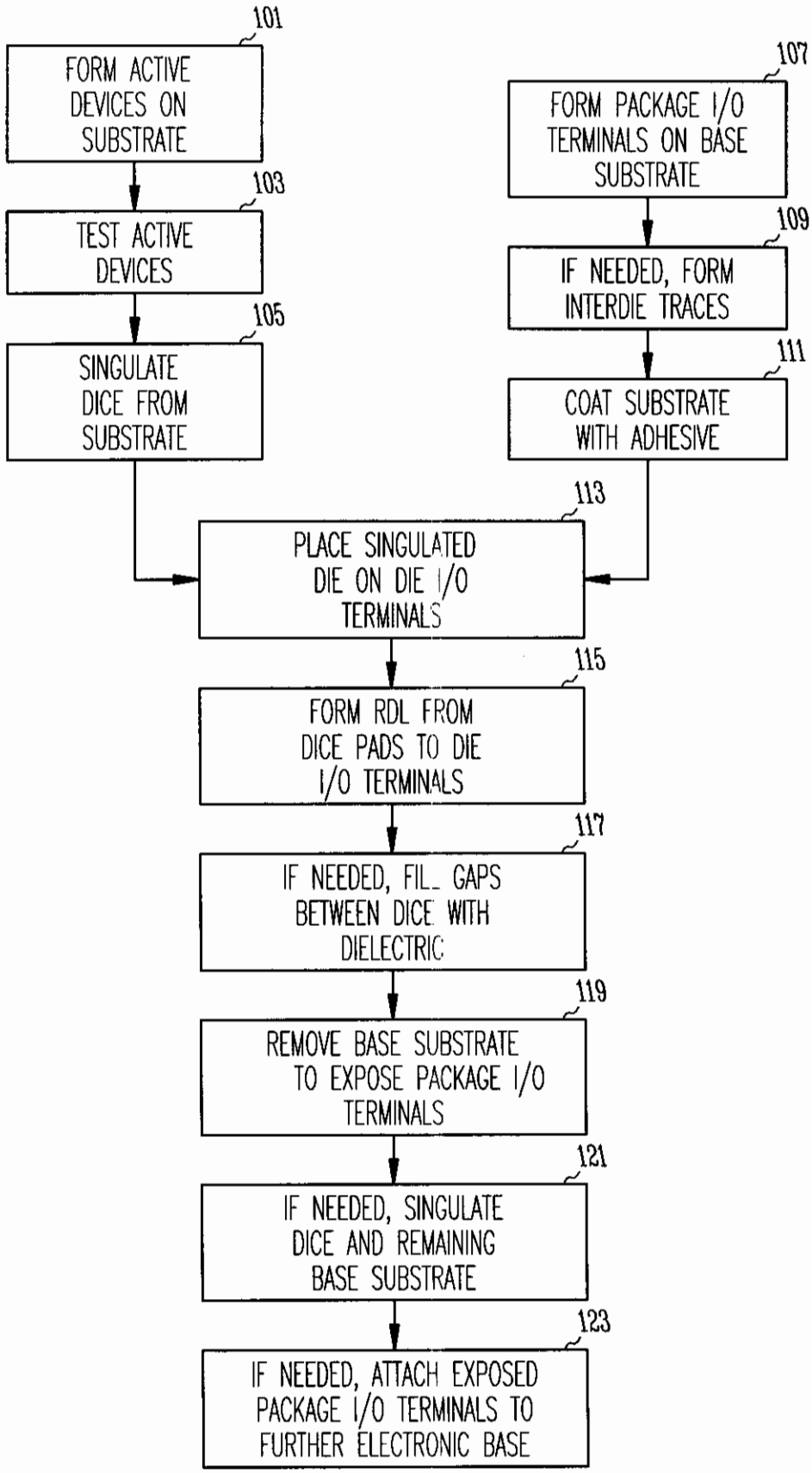

101
FORM ACTIVE DEVICES ON SUBSTRATE
103
TEST ACTIVE DEVICES
105
SINGULATE DICE FROM SUBSTRATE
107
FORM PACKAGE I/O TERMINALS ON BASE SUBSTRATE
109
IF NEEDED, FORM INTERDIE TRACES
111
COAT SUBSTRATE WITH ADHESIVE
113
PLACE SINGULATED DIE ON DIE I/O TERMINALS
115
FORM RDL FROM DICE PADS TO DIE I/O TERMINALS
117
IF NEEDED, FIL_ GAPS BETWEEN DICE WITH DIELECTRIC
119
REMOVE BASE SUBSTRATE TO EXPOSE PACKAGE I/O TERMINALS
121
IF NEEDED, SINGULATE DICE AND REMAINING BASE SUBSTRATE
123
IF NEEDED, ATTACH EXPOSED PACKAGE I/O TERMINALS TO FURTHER ELECTRONIC BASE

Fig. 1

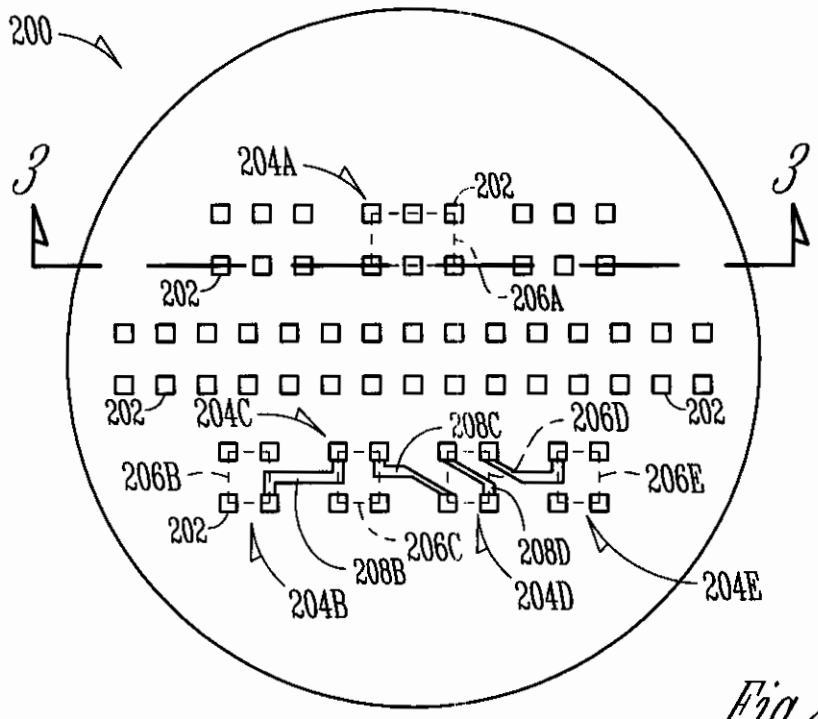


Fig. 2

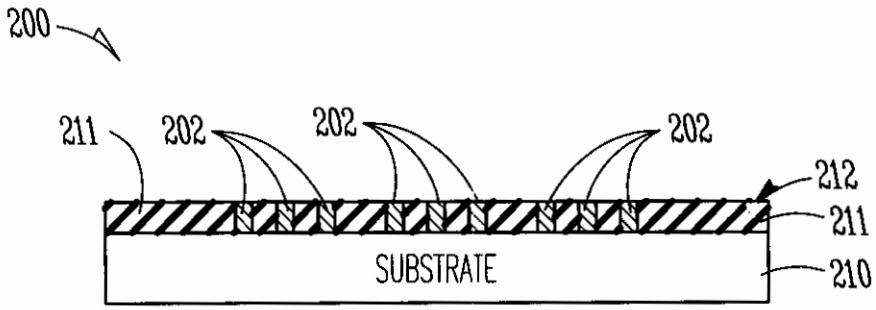


Fig. 3

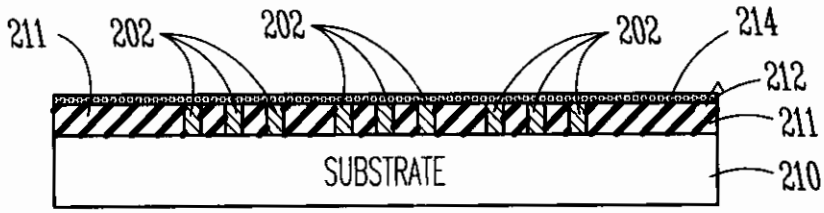


Fig. 4

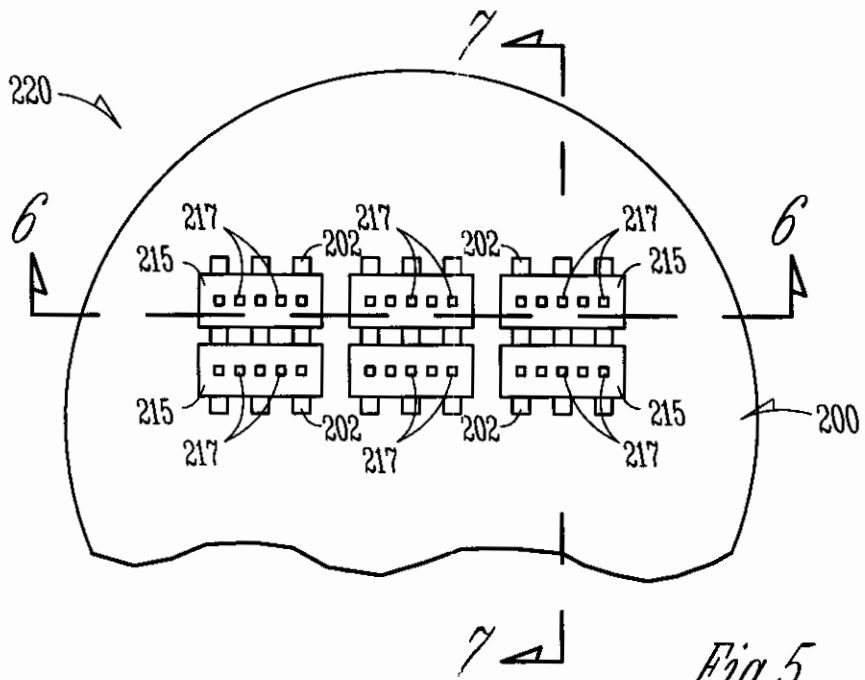


Fig. 5

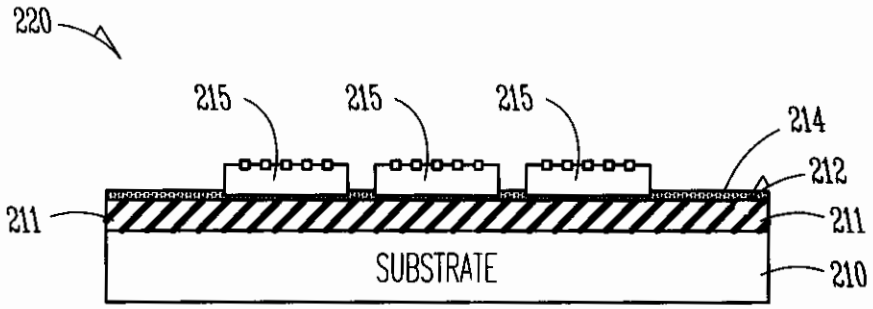


Fig. 6

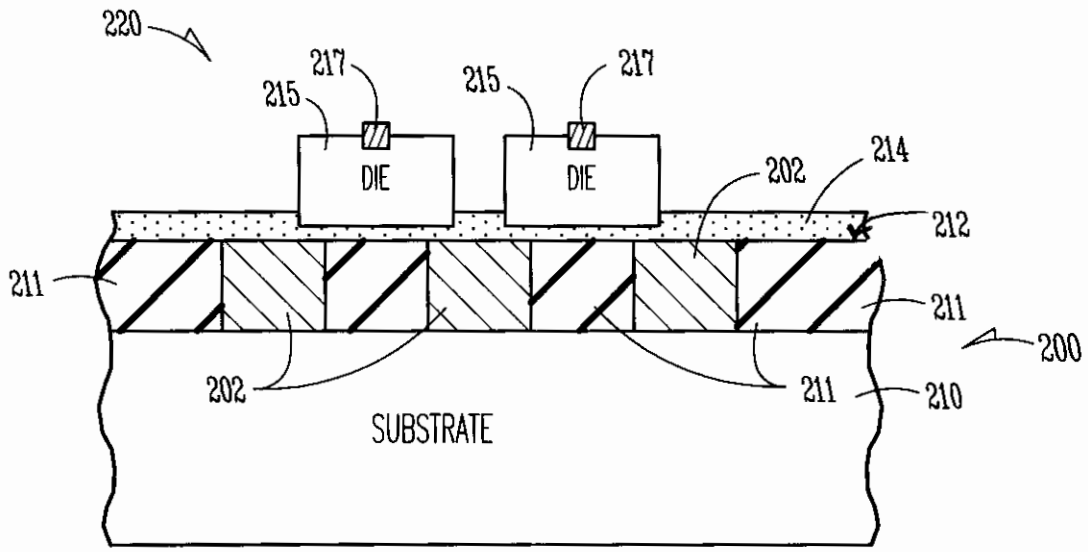


Fig. 7

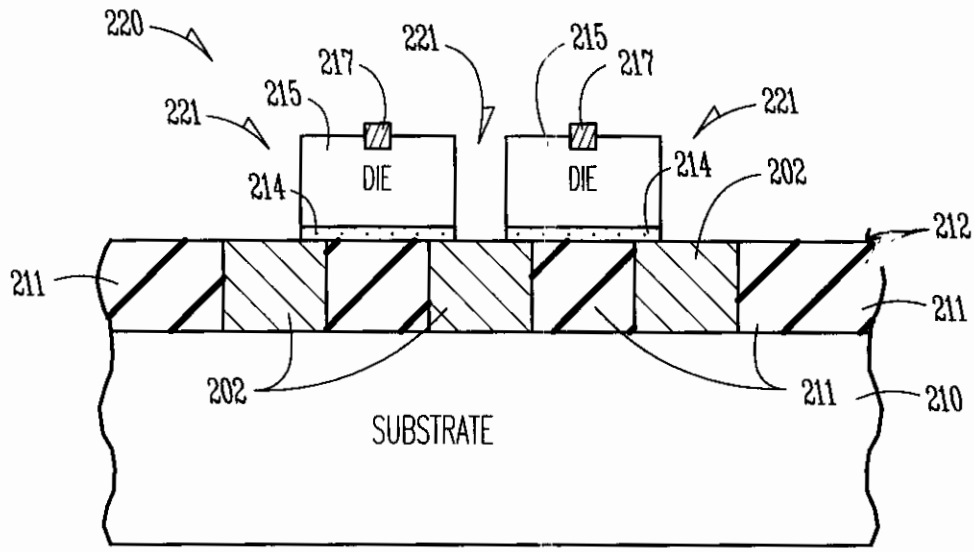

220
221
215
217
217
215
221
221
DIE
DIE
214
214
202
212
211
211
202
211
210
SUBSTRATE

Fig. 8

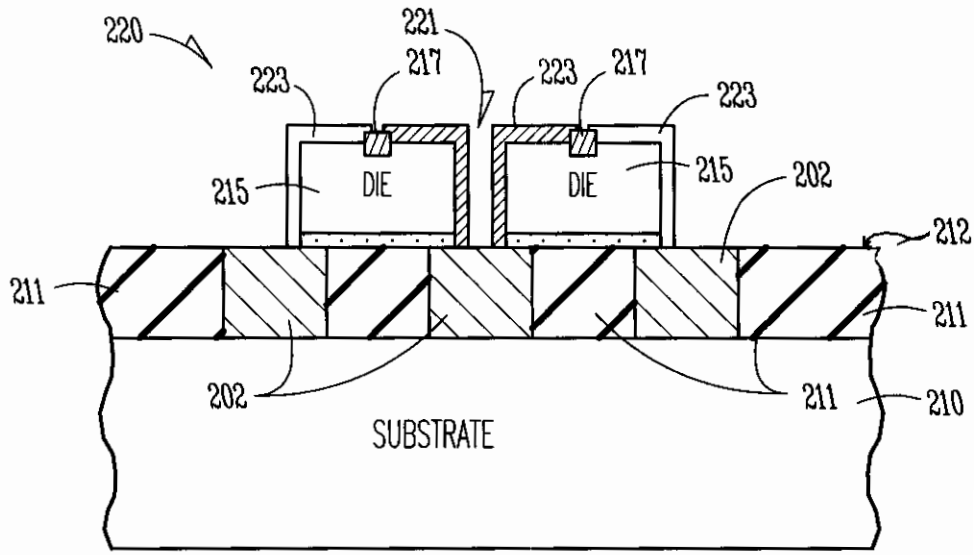

220
221
223
217
223
217
223
215
DIE
DIE
215
202
212
211
211
202
211
210
SUBSTRATE

Fig. 9

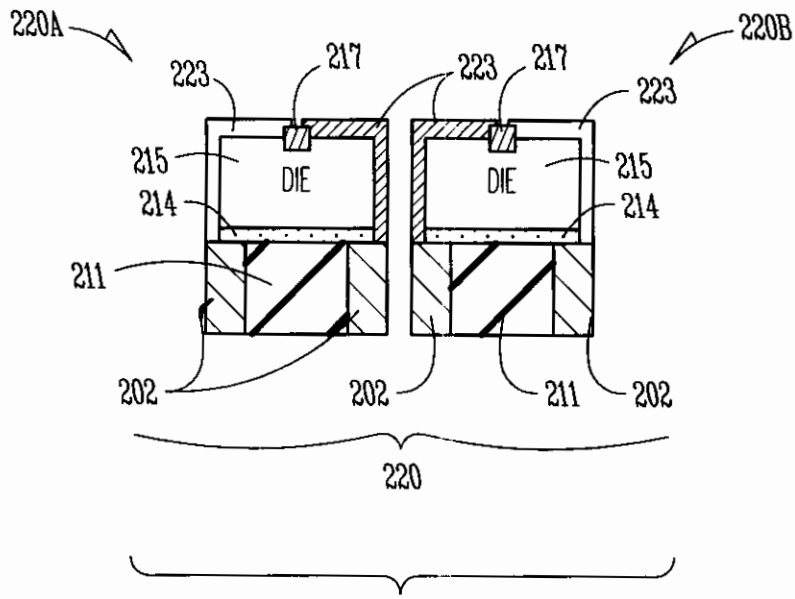

220A
220B
223
217
223
217
223
215
DIE
DIE
215
214
214
211
202
202
211
202
220

Fig. 10

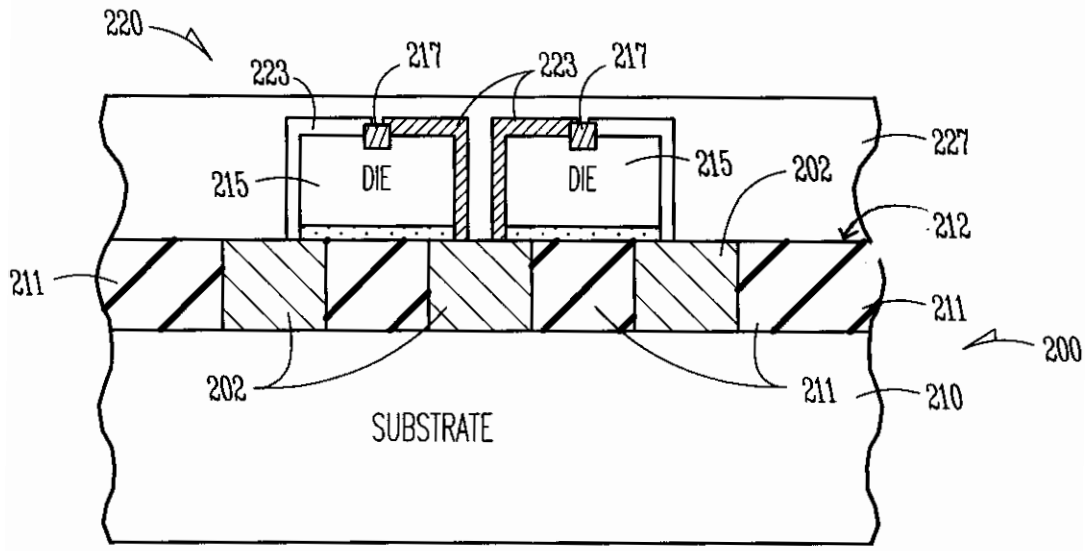

220
223
217
223
217
227
215
DIE
DIE
215
202
212
211
211
200
202
211
210
SUBSTRATE

Fig. 11

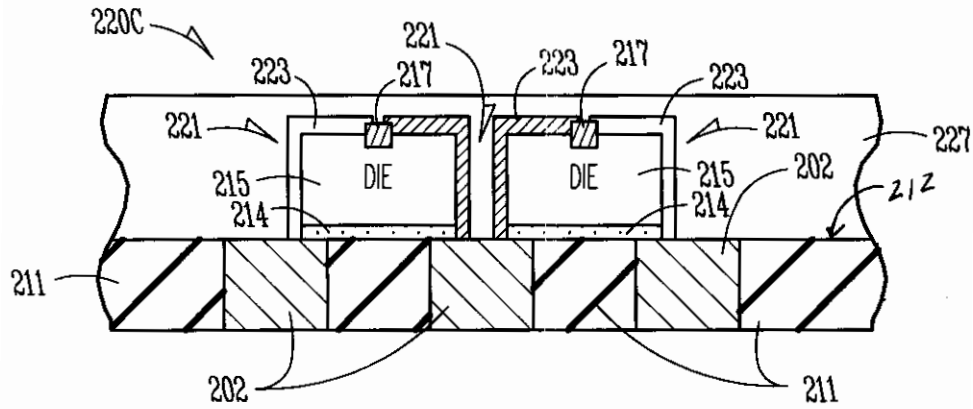

220C
221
223
217
223
217
223
221
221
227
DIE
DIE
215
215
214
214
202
212
211
202
211

Fig. 12

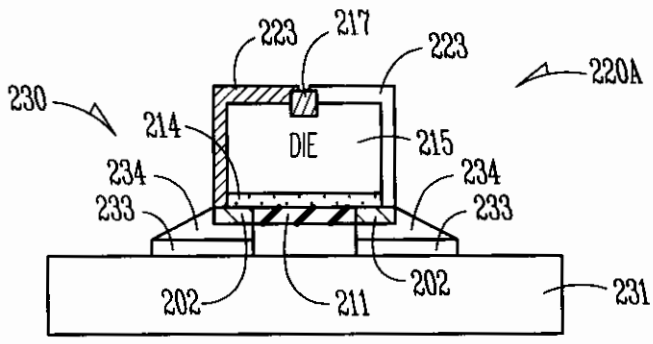

223
217
223
220A
230
214
DIE
215
234
234
233
233
202
211
202
231

Fig. 13

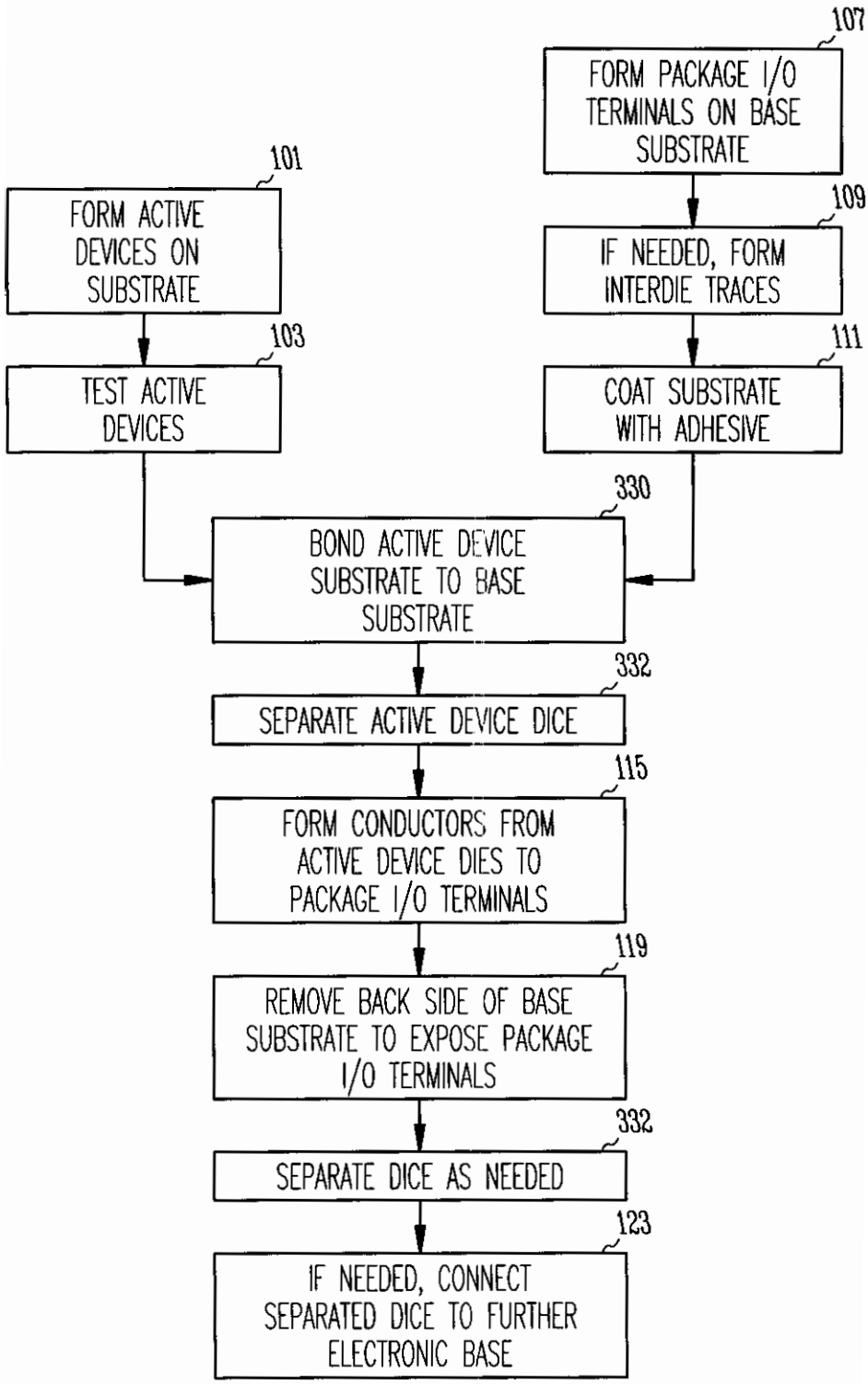

107
FORM PACKAGE I/O TERMINALS ON BASE SUBSTRATE
101
FORM ACTIVE DEVICES ON SUBSTRATE
109
IF NEEDED, FORM INTERDIE TRACES
103
TEST ACTIVE DEVICES
111
COAT SUBSTRATE WITH ADHESIVE
330
BOND ACTIVE DEVICE SUBSTRATE TO BASE SUBSTRATE
332
SEPARATE ACTIVE DEVICE DICE
115
FORM CONDUCTORS FROM ACTIVE DEVICE DIES TO PACKAGE I/O TERMINALS
119
REMOVE BACK SIDE OF BASE SUBSTRATE TO EXPOSE PACKAGE I/O TERMINALS
332
SEPARATE DICE AS NEEDED
123
IF NEEDED, CONNECT SEPARATED DICE TO FURTHER ELECTRONIC BASE

Fig. 14

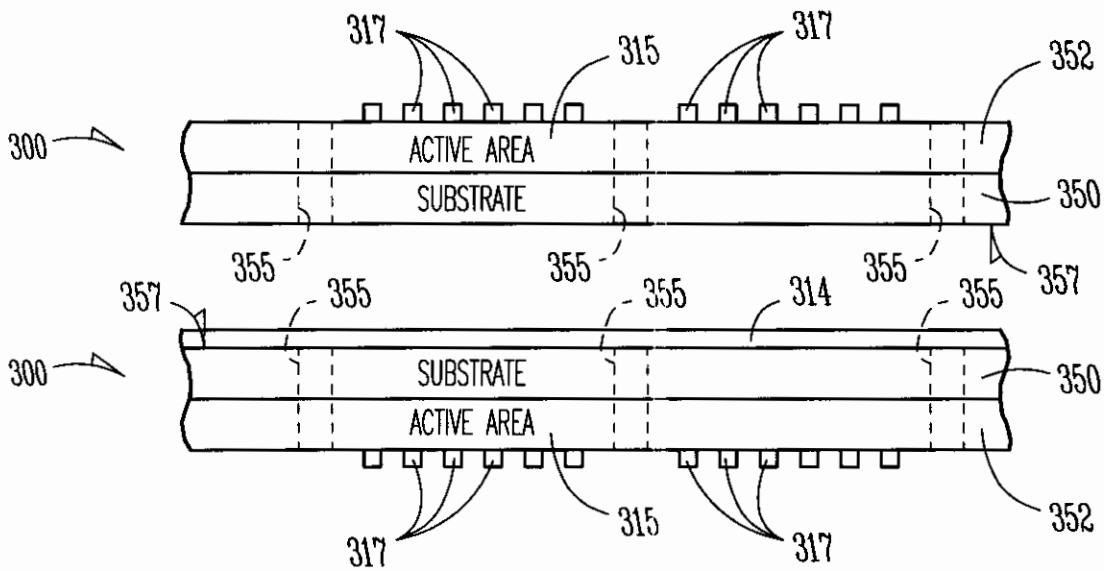

317
315
317
352
300
ACTIVE AREA
SUBSTRATE
350
355
355
355
357
357
355
355
314
355
300
SUBSTRATE
ACTIVE AREA
350
315
317
317
352

Fig. 15

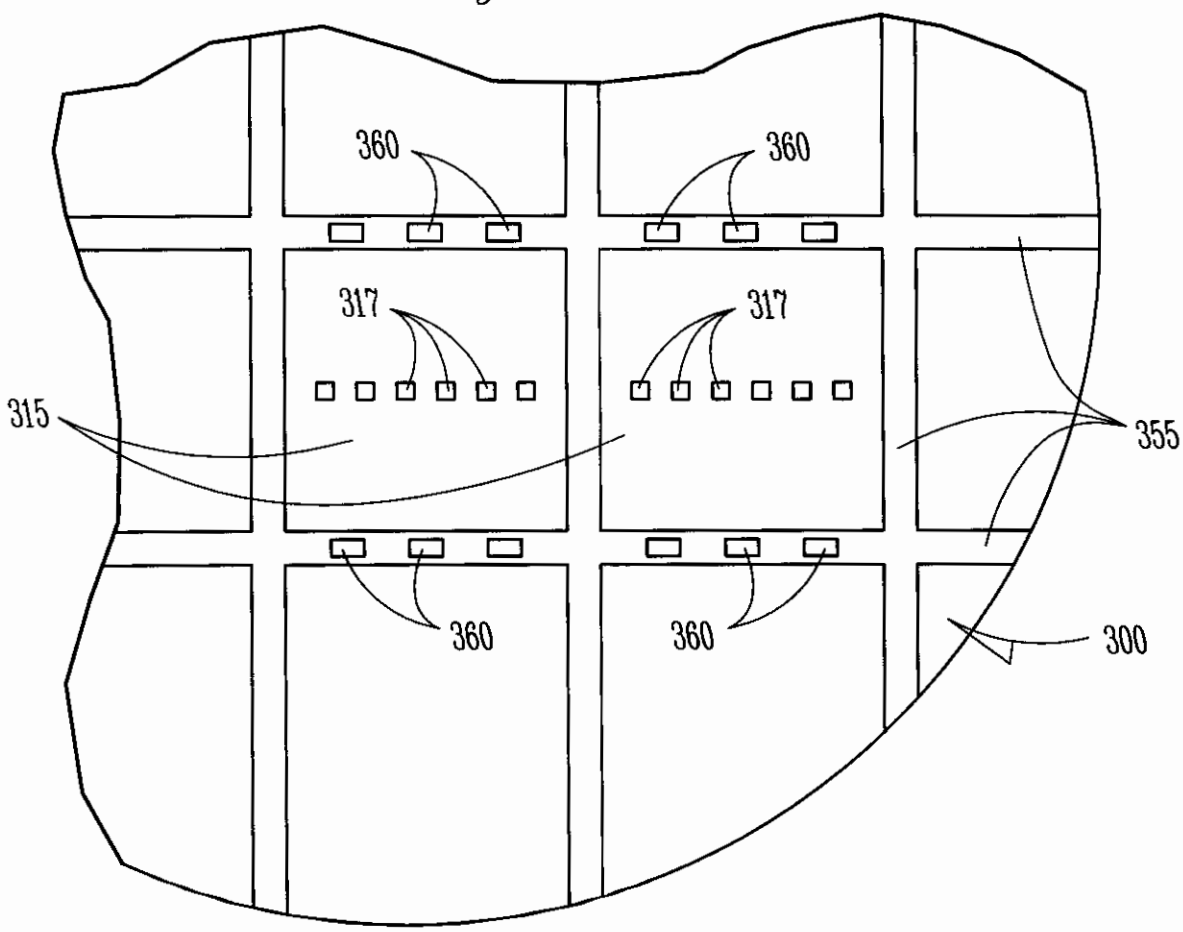

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360
317
317
315
355
360
360
300

Fig. 16

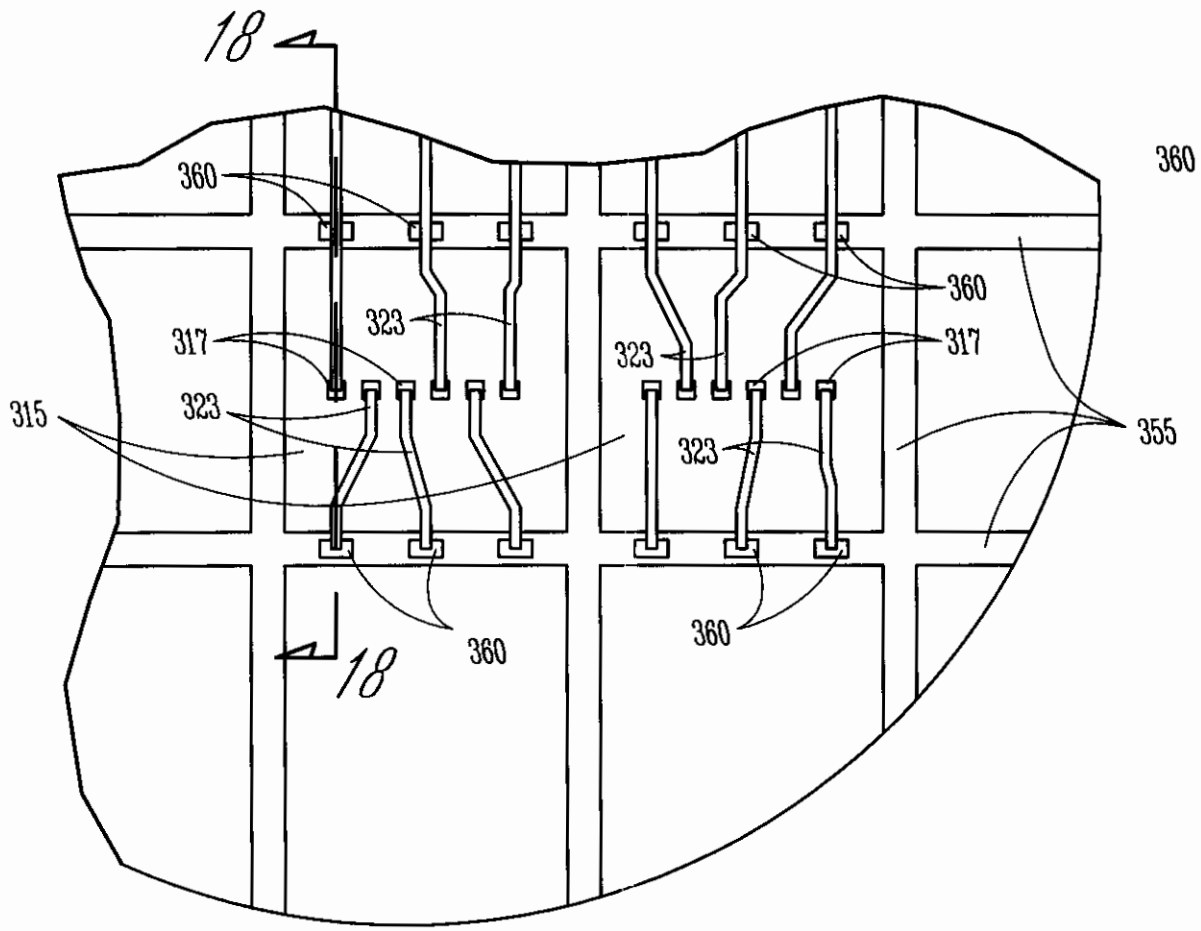

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360
360
317
323
323
317
323
315
323
355
360
360
18
360
360

Fig. 17

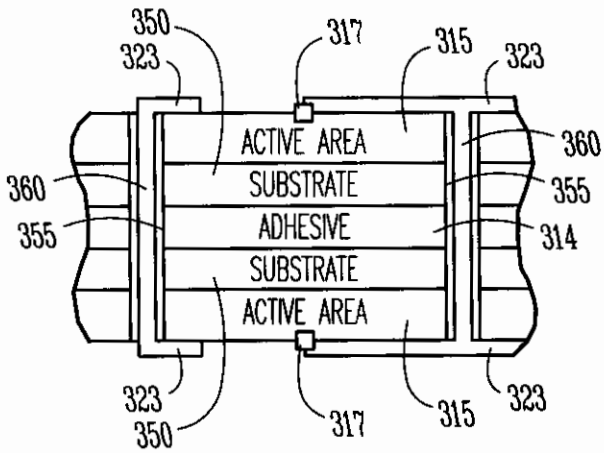

350
323
317
315
323
ACTIVE AREA
SUBSTRATE
ADHESIVE
SUBSTRATE
ACTIVE AREA
360
360
355
355
314
323
350
317
315
323

Fig. 18

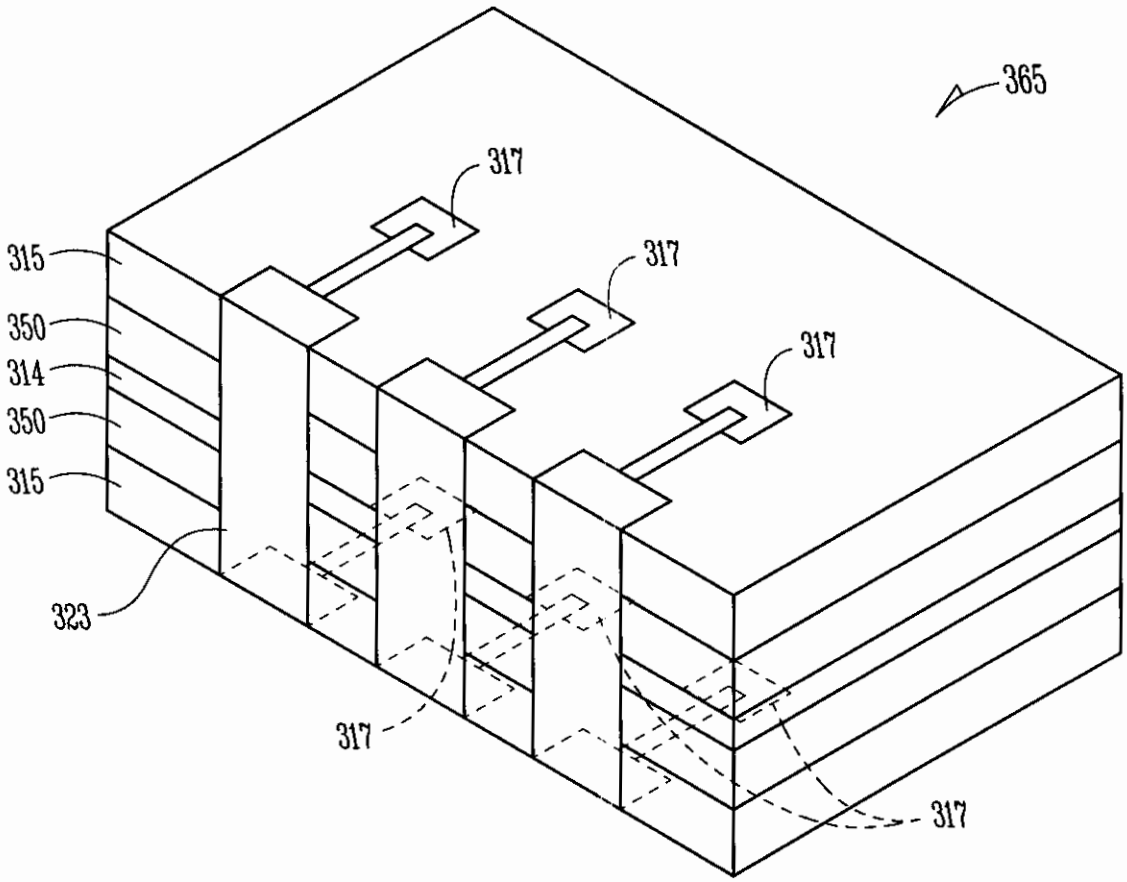

365
317
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317
315
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314
350
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323
317
317

Fig. 19

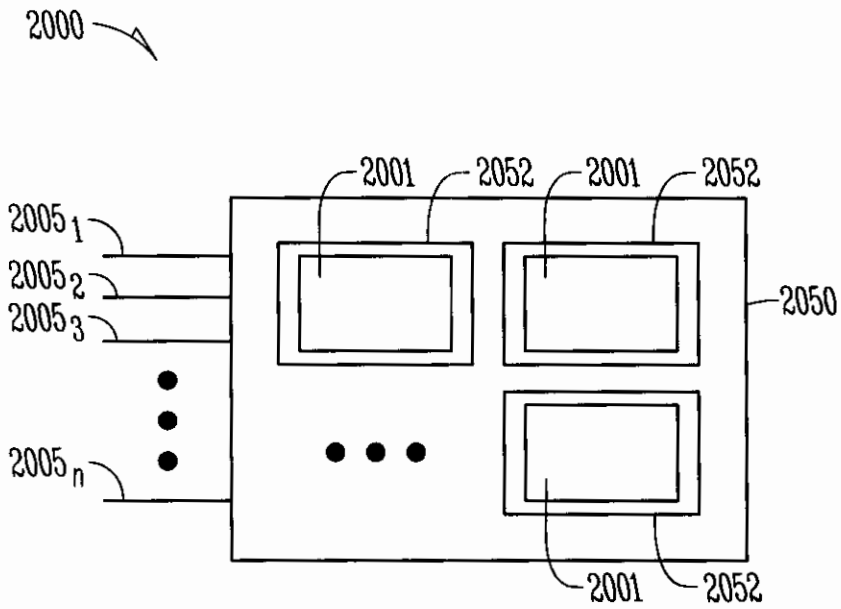

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2001
2052
2001
2052
2005_1
2005_2
2005_3
2005_n
2050
2001
2052

Fig. 20

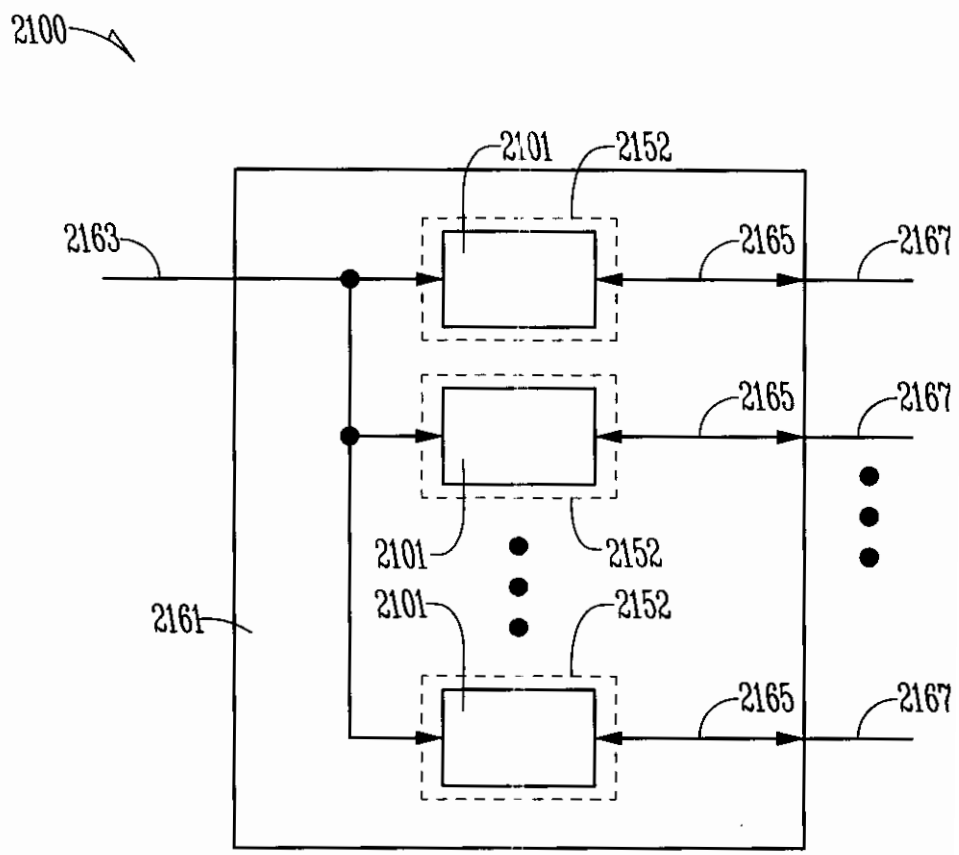

2100
2101
2152
2163
2165
2167
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2101
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2161
2101
2152
2165
2167

Fig.21

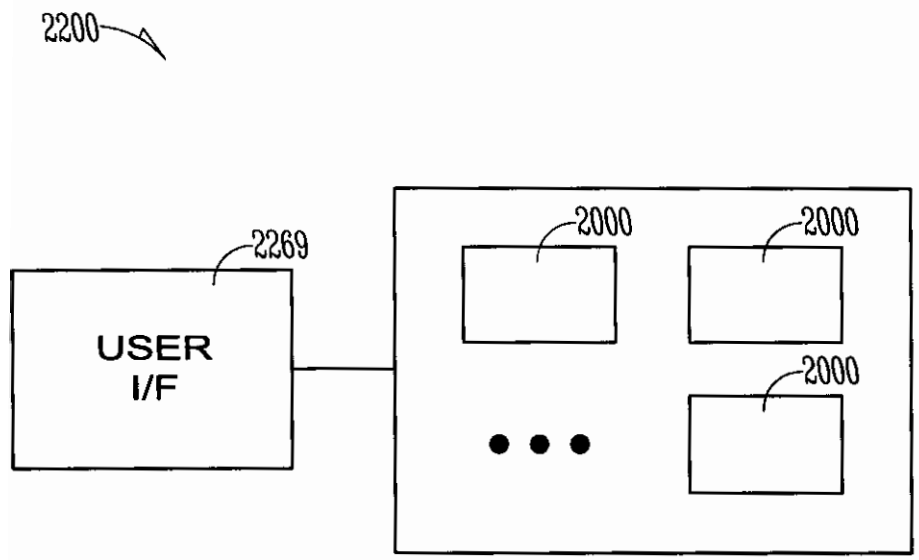

2200
2269
USER
I/F
2000
2000
2000

Fig.22

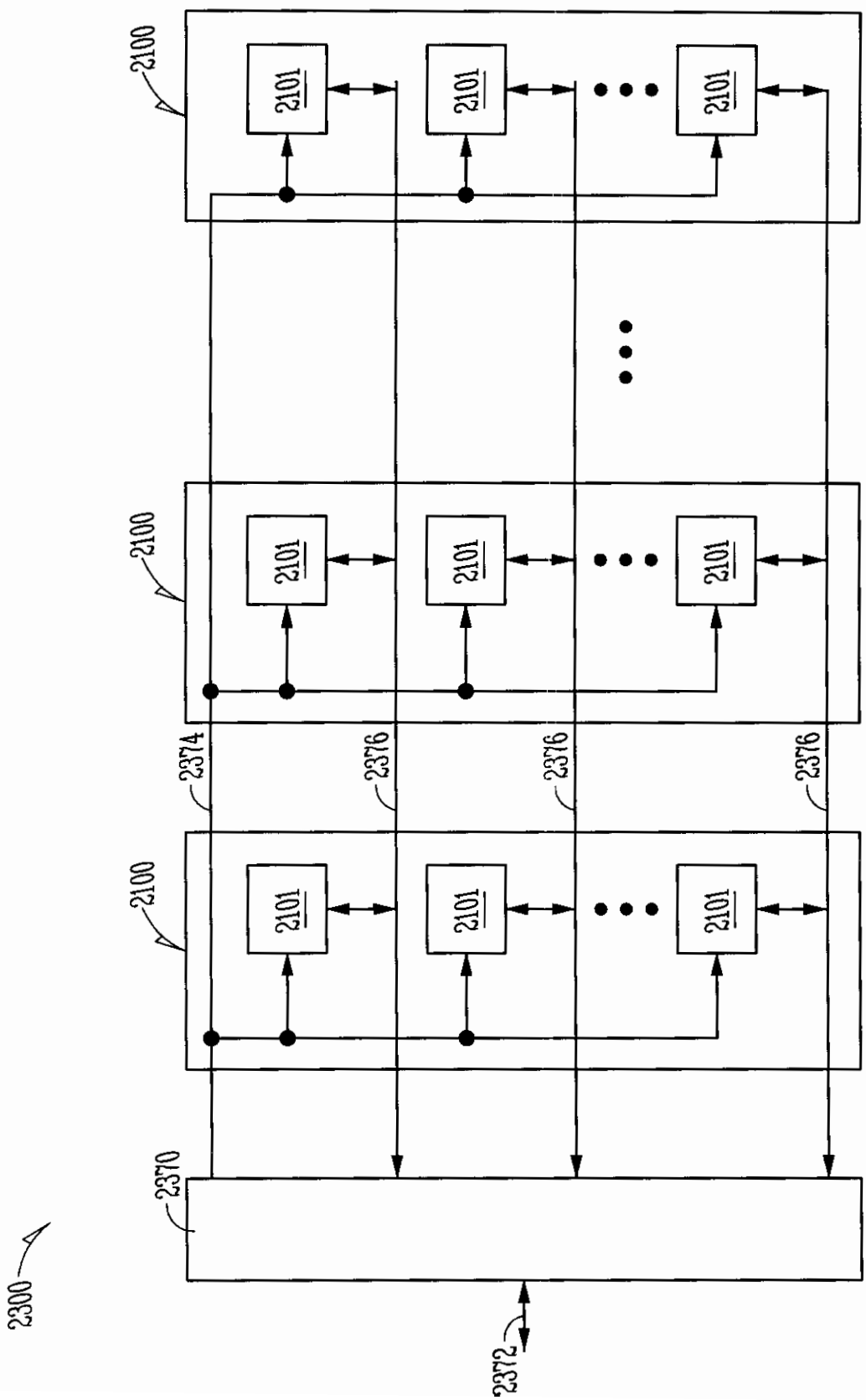

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2370
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2374
2376
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2376
2100
2100
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2101
2101
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2101
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2101
2101
2101
2101

Fig.23

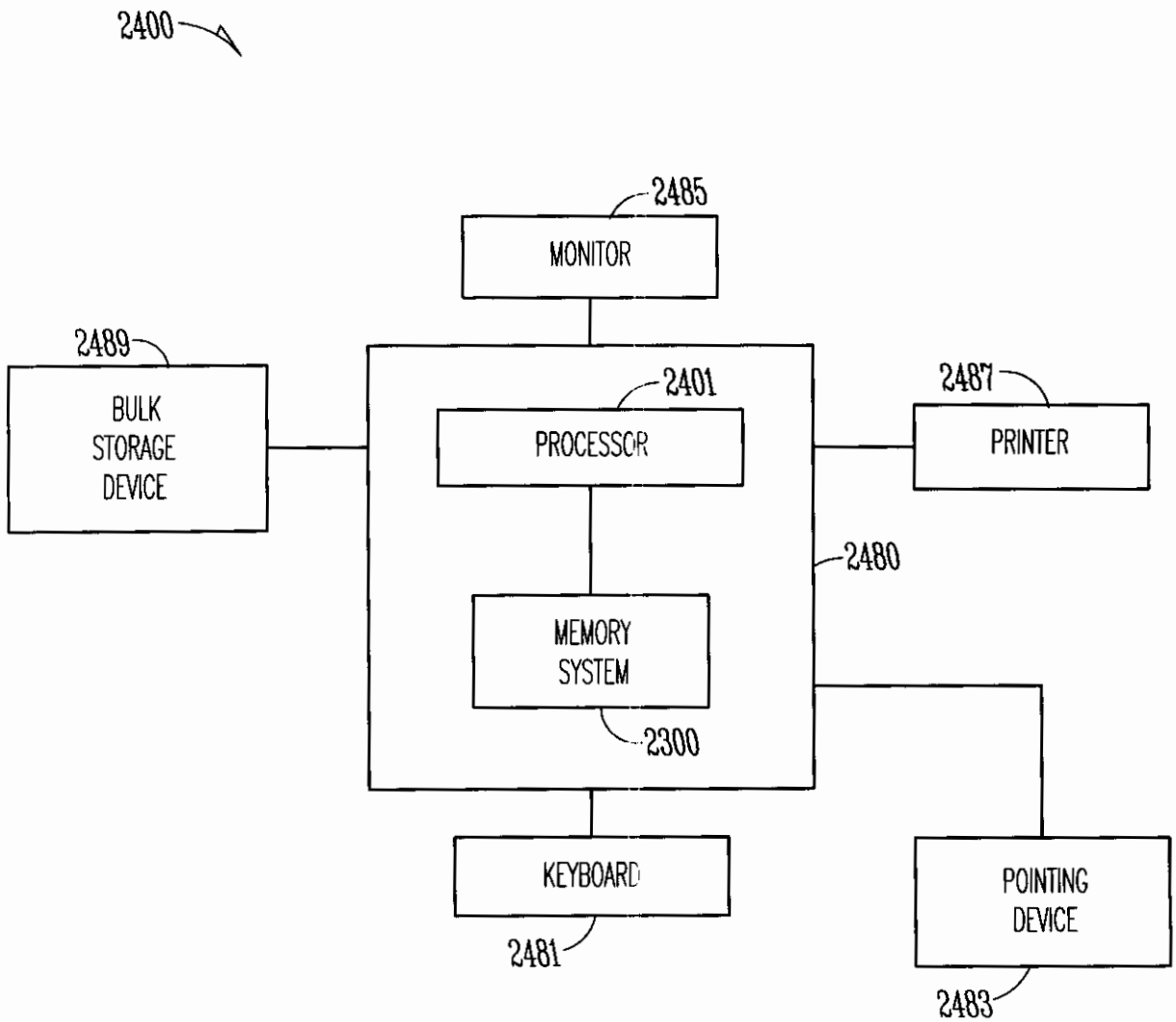

2400
2485
MONITOR
2489
BULK STORAGE DEVICE
2401
PROCESSOR
2487
PRINTER
2480
MEMORY SYSTEM
2300
KEYBOARD
2481
POINTING DEVICE
2483

Fig. 24